## **REMARKS**

In view of the above amendments and following remarks, reconsideration and further examination are requested.

Claims 26, 30-32, 34 and 36 were rejected under 35 U.S.C. §102(e) as being anticipated by Iwata et al. Claims 26-30, 34 and 35 were rejected under 35 U.S.C. §102(e) as being anticipated by Beddingfield. And, claims 26, 30, 33 and 48 were rejected under 35 U.S.C. §102(e) as being anticipated by Livengood et al. These rejections are respectfully traversed in part, and the relied upon references are not applicable with regard to the currently amended and added claims for the following reasons.

With regard to Iwata et al., though the Examiner has stated that reference numeral "10" corresponds to an electronic component to be mounted on a printed board, reference numeral "10" actually denotes a substrate of a wiring board to which electronic components are to be mounted, and thus does not correspond to the electronic component as claimed. Please see Fig. 3 and column 6, lines 34-39 of Iwata et al. Accordingly, because Iwata et al. fails to teach or suggest an **electronic component** having a recognition mark, neither of independent claims 26 and 31 are anticipated by Iwata et al., whereby claims 26-33, 35, 36 and 48-58 are allowable over Iwata et al.

With regard to the rejections based on Beddingfield, independent claim 26 has been amended to recite that the at least one recognition mark is formed simultaneously with formation of **lands**. Beddingfield fails to teach or suggest that alignment bumps 38 are formed simultaneously with pads or lands 39.

In this regard, while column 3, lines 10-20 of Beddingfield states that "the alignment bumps are formed at the same time that input/output (I/O) bumps on the die are formed", Beddingfield nowhere states that the alignment bumps are formed simultaneously with pads or lands on which the (I/O) bumps are formed. Indeed, from a fair reading of Beddingfield it is clear that the alignment bumps are formed after formation or provision of the lands. Please see process flow 80 as described with reference to Figure 6 beginning in column 5, line 51. Thus, claim 26 is not anticipated by Beddingfield, whereby claims 26-33, 35, 36 and 48-58 are allowable over Beddinfield.

With regard to the rejections based on Livengood et al., independent claim 26 has been amended to include the limitation of claim 34 that the at least one recognition mark is formed simultaneously with the lands. As recognized by the Examiner, such simultaneous formation is

not disclosed by Livengood et al., and accordingly, claims 26-33, 35, 36 and 48-58 are allowable over Livengood et al.

In view of the above amendments and remarks, it is respectfully submitted that the present application is in condition for allowance and an early Notice of Allowance is earnestly solicited.

If after reviewing this Amendment, the Examiner believes that any issues remain which must be resolved before the application can be passed to issue, the Examiner is invited to contact the Applicant's undersigned representative by telephone to resolve such issues.

Respectfully submitted,

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